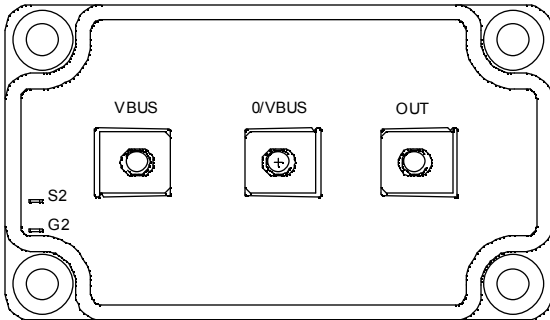
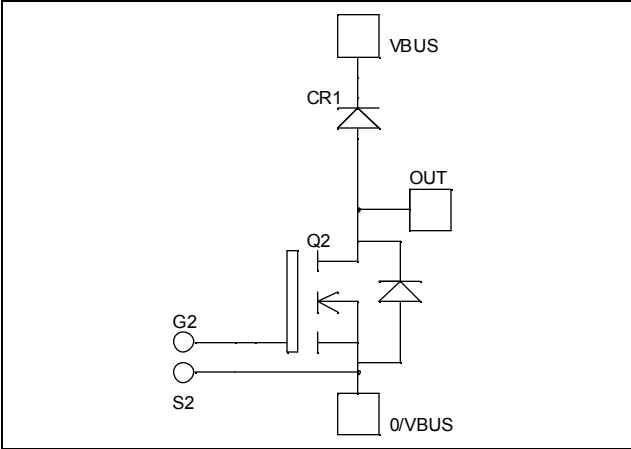


Boost chopper MOSFET Power Module

$V_{DSS} = 1200V$
 $R_{DSon} = 150m\Omega$ typ @ $T_j = 25^\circ C$
 $I_D = 60A$ @ $T_c = 25^\circ C$



Application

- AC and DC motor control
- Switched Mode Power Supplies
- Power Factor Correction

Features

- Power MOS 7[®] MOSFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{DSS}	Drain - Source Breakdown Voltage	1200	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	60
		$T_c = 80^\circ C$	45
I_{DM}	Pulsed Drain current	240	
V_{GS}	Gate - Source Voltage	± 30	V
R_{DSon}	Drain - Source ON Resistance	175	m Ω
P_D	Maximum Power Dissipation	$T_c = 25^\circ C$	1250
I_{AR}	Avalanche current (repetitive and non repetitive)	22	A
E_{AR}	Repetitive Avalanche Energy	50	mJ
E_{AS}	Single Pulse Avalanche Energy	3000	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0\text{V}, V_{DS} = 1200\text{V}$			500	μA
		$V_{GS} = 0\text{V}, V_{DS} = 1000\text{V}$	$T_j = 25^\circ\text{C}$		3000	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10\text{V}, I_D = 30\text{A}$		150	175	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 10\text{mA}$	3		5	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 30\text{V}, V_{DS} = 0\text{V}$			± 250	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}$		20.6		nF
C_{oss}	Output Capacitance	$V_{DS} = 25\text{V}$		3.08		
C_{rss}	Reverse Transfer Capacitance	$f = 1\text{MHz}$		0.52		
Q_g	Total gate Charge	$V_{GS} = 10\text{V}$		748		nC
Q_{gs}	Gate – Source Charge	$V_{Bus} = 600\text{V}$		96		
Q_{gd}	Gate – Drain Charge	$I_D = 60\text{A}$		480		
$T_{d(on)}$	Turn-on Delay Time	Inductive switching @ 125°C		20		ns
T_r	Rise Time	$V_{GS} = 15\text{V}$		15		
$T_{d(off)}$	Turn-off Delay Time	$V_{Bus} = 800\text{V}$		160		
T_f	Fall Time	$I_D = 60\text{A}$		45		
E_{on}	Turn-on Switching Energy	Inductive switching @ 25°C		3.96		mJ
E_{off}	Turn-off Switching Energy	$V_{GS} = 15\text{V}, V_{Bus} = 800\text{V}$		2.74		
E_{on}	Turn-on Switching Energy	Inductive switching @ 125°C		6.26		mJ
E_{off}	Turn-off Switching Energy	$V_{GS} = 15\text{V}, V_{Bus} = 800\text{V}$		3.43		

Chopper diode ratings and characteristics

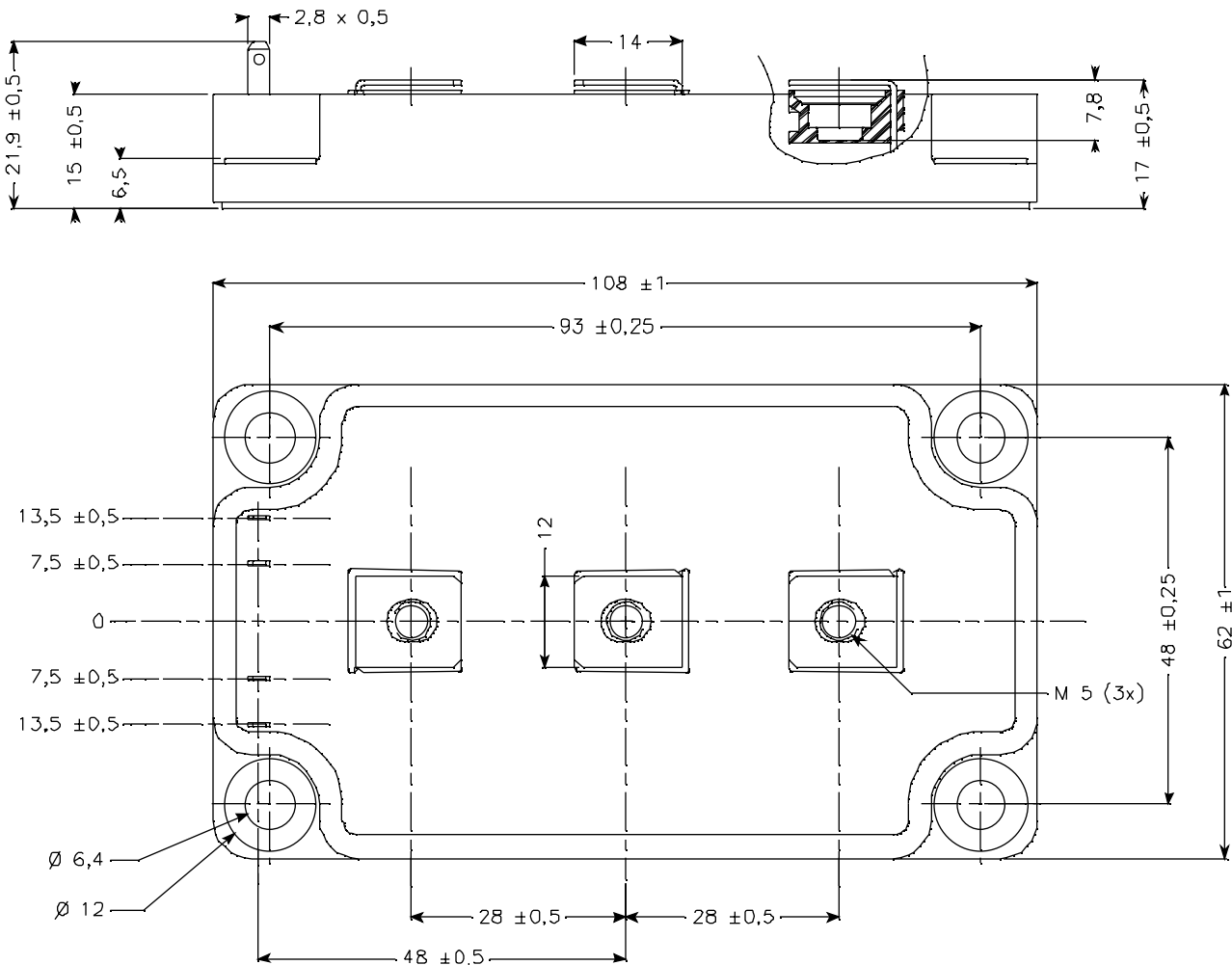
Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage		1200			V
I_{RM}	Maximum Reverse Leakage Current	$V_R = 1200\text{V}$	$T_j = 25^\circ\text{C}$		250	μA
			$T_j = 125^\circ\text{C}$		750	
I_F	DC Forward Current			60		A
V_F	Diode Forward Voltage	$I_F = 60\text{A}$		2	2.5	V
		$I_F = 120\text{A}$		2.3		
		$I_F = 60\text{A}$	$T_j = 125^\circ\text{C}$	1.8		
t_{rr}	Reverse Recovery Time	$I_F = 60\text{A}$ $V_R = 800\text{V}$	$T_j = 25^\circ\text{C}$	400		ns
			$T_j = 125^\circ\text{C}$	470		
Q_{rr}	Reverse Recovery Charge	$di/dt = 200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$	1200		nC
			$T_j = 125^\circ\text{C}$	4000		

Thermal and package characteristics

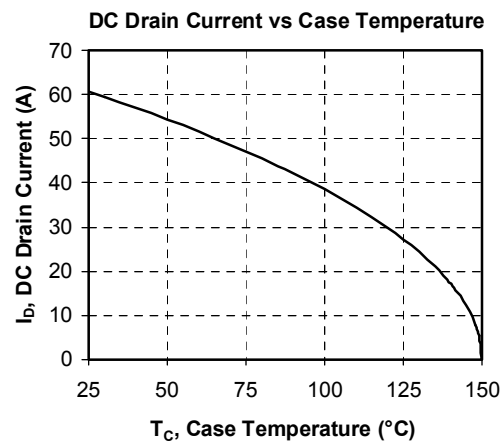
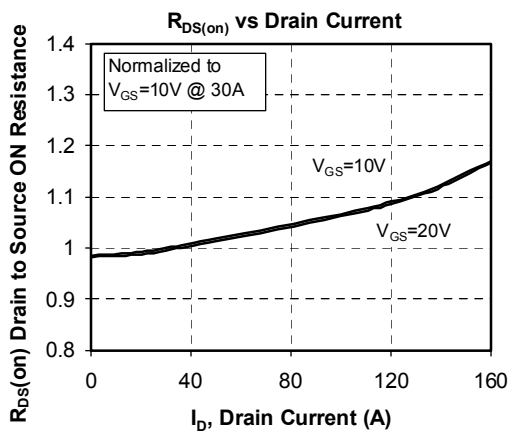
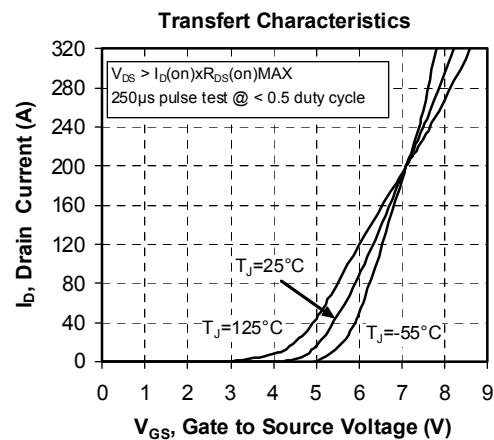
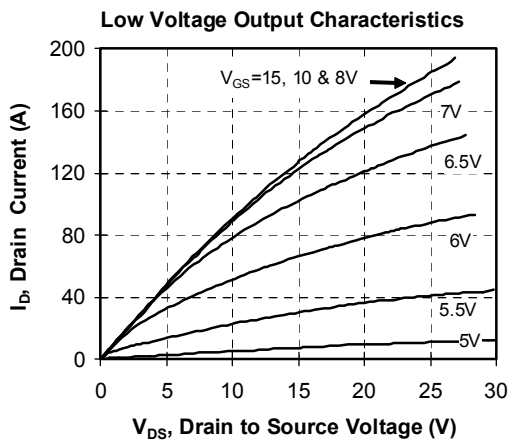
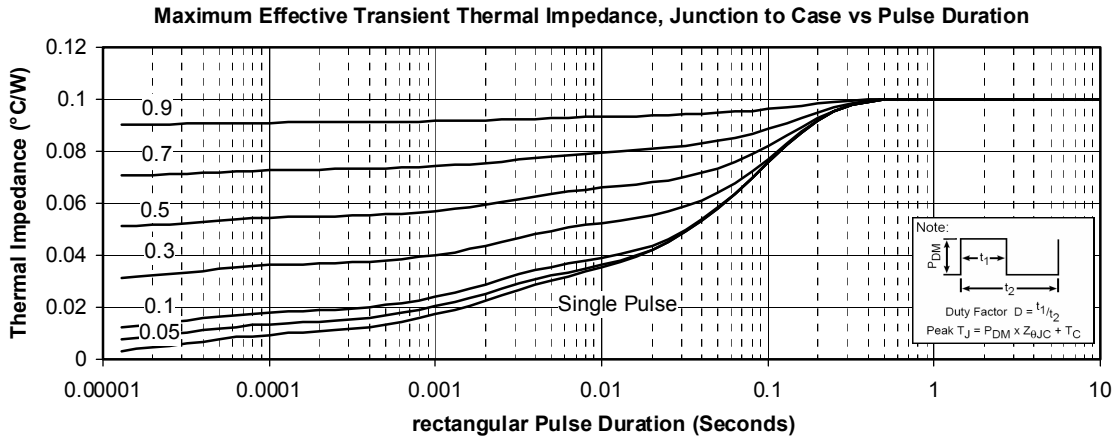
Symbol Characteristic

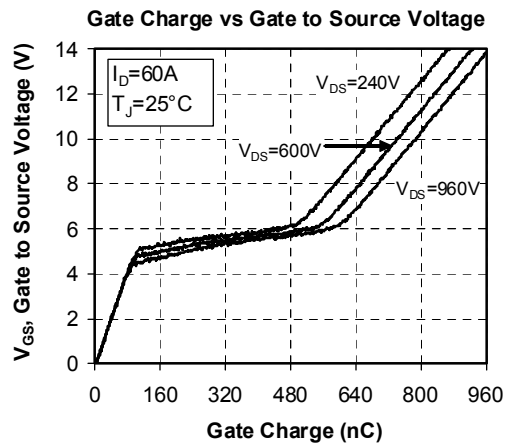
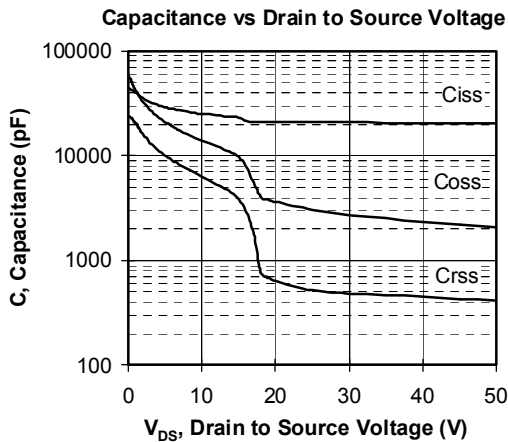
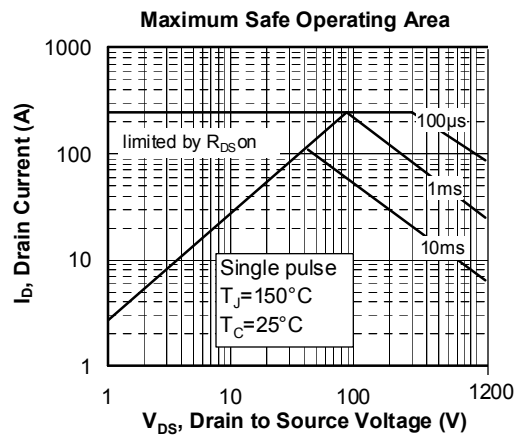
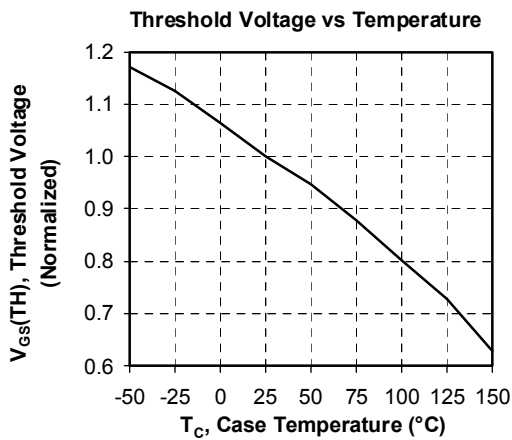
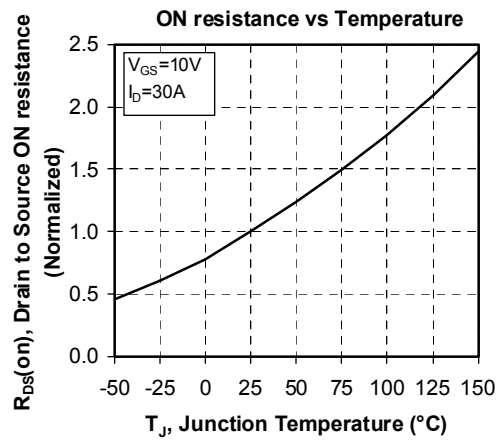
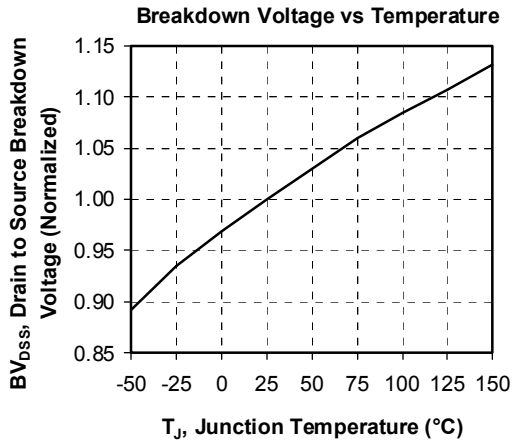
			Min	Typ	Max	Unit
R _{thJC}	Junction to Case Thermal Resistance	Transistor			0.1	°C/W
		Diode			0.9	
V _{ISOL}	RMS Isolation Voltage, any terminal to case t=1 min, I _{isol} <1mA, 50/60Hz		2500			V
T _J	Operating junction temperature range		-40		150	°C
T _{STG}	Storage Temperature Range		-40		125	
T _C	Operating Case Temperature		-40		100	
Torque	Mounting torque	To heatsink	M6	3	5	N.m
		For terminals	M5	2	3.5	
Wt	Package Weight				280	g

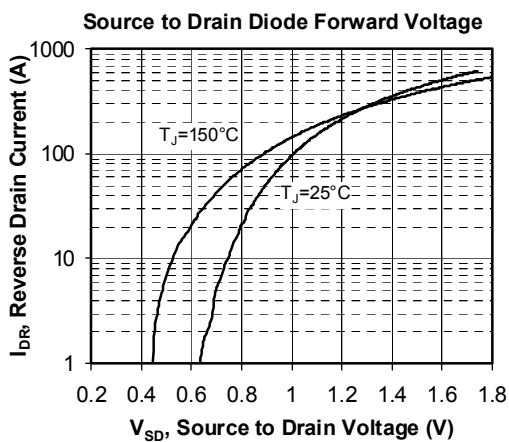
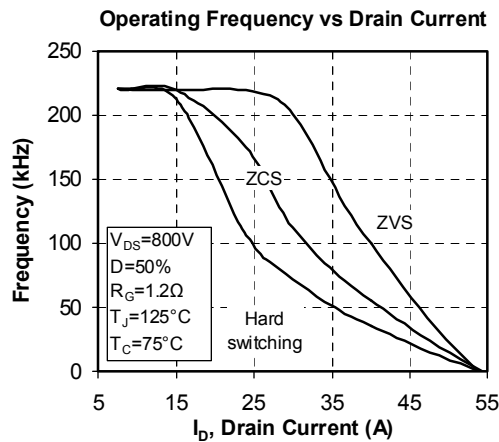
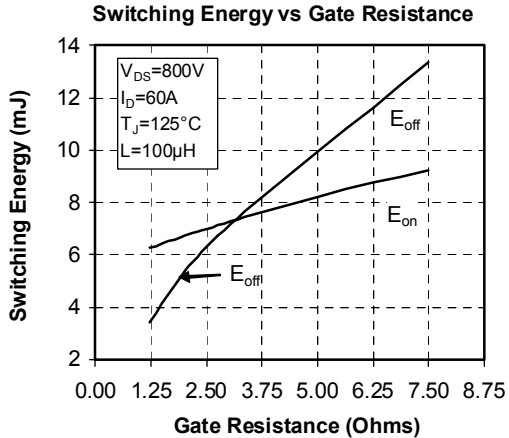
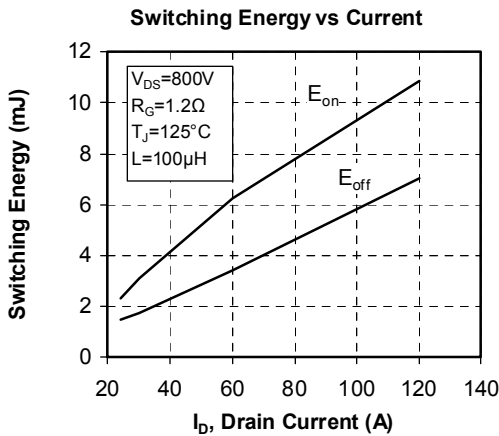
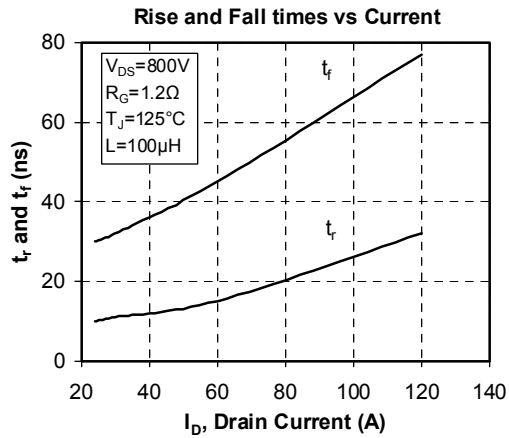
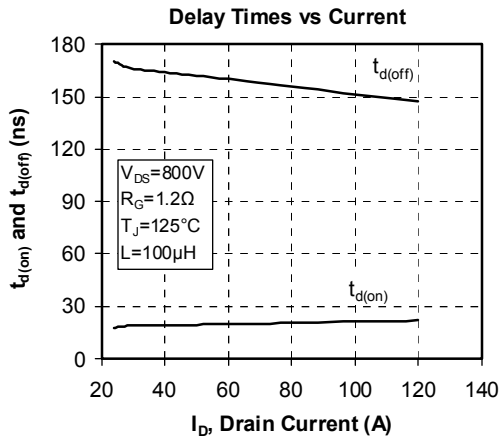
SP6 Package outline (dimensions in mm)



See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com

Typical Performance Curve






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